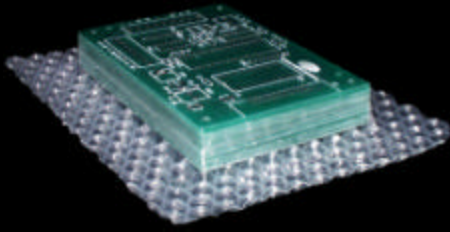


# Printed Circuit Packaging Bubble

## THE MOISTURE BARRIER



### Product Features

- Superior Air Retention (3 layers of protection)
- Excellent moisture barrier
- Greater strength
- Improved package integrity.
- Better cushioning
- Available in clear or antistatic.

- Amine Free
- No Animal Fats
- Non Reactive
- Non Corrosive



<b>Creep (Thickness loss)</b> (PPP-C-795D)	10% maximum air loss, 1.0PSI, 96hrs
<b>Contact Corrosivity</b> (PPP-C-795D)	No Corrosion, etching
<b>Heat Sealability (seam strength)</b> (ASTM D952)	No separation at 11lb per inch width
<b>Coefficient of Friction</b> (ASTM D1894)	Less than 1.0
<b>Static Decay</b> (Method 4045 of FTM Standard 101)	Maximum 2 second decay +/- 5000 to zero volts. Conditioning at 15% R.H. for 24hrs
<b>Surface Resistivity</b>	<10 OHMS/SQ at 73 degrees F, 15% R.H.

**Silicones, Polysulfides, Ionic Sulfur Compounds** N.A.  
*(Not used in Manufacturing Process)*

<b>Part #'s</b>	
BP-1622	Clear (EC-1824)
BP-1622AS	Anti-Stat (EC-1824)
BP-2228	Clear (SP-2430)
BP-2228AS	Anti-Stat (SP-2430)



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